

Sn95.5/Ag4.0/Cu0.5 Solder Spheres for BGAs

Product Highlights

Chip Quik® BGA solder spheres are manufactured from virgin materials to meet or exceed the requirements of building or repairing BGA packages. Chip Quik® BGA solder spheres also exceed both the IPC and MIL standards for purity levels and size tolerances. Nominal sizes are available from 0.20 to 0.76 mm (8 to 30 mil).

Product Specifications

Part Number	Alloy	Melting Point	Diameter	Quantity (by weight)
CQ-SS-SAC405-0.20MM-25000	Sn95.5/Ag4.0/Cu0.5	217°C (423°F)	0.20 mm	25,000
CQ-SS-SAC405-0.25MM-25000			0.25 mm	25,000
CQ-SS-SAC405-0.30MM-25000			0.30 mm	25,000
CQ-SS-SAC405-0.35MM-25000			0.35 mm	25,000
CQ-SS-SAC405-0.40MM-25000			0.40 mm	25,000
CQ-SS-SAC405-0.45MM-25000			0.45 mm	25,000
CQ-SS-SAC405-0.50MM-25000			0.50 mm	25,000
CQ-SS-SAC405-0.60MM-25000			0.60 mm	25,000
CQ-SS-SAC405-0.76MM-25000			0.76 mm	25,000

Shelf Life: >24 months

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): Yes
 RoHS 3 Directive (EU) 2015/863: Yes